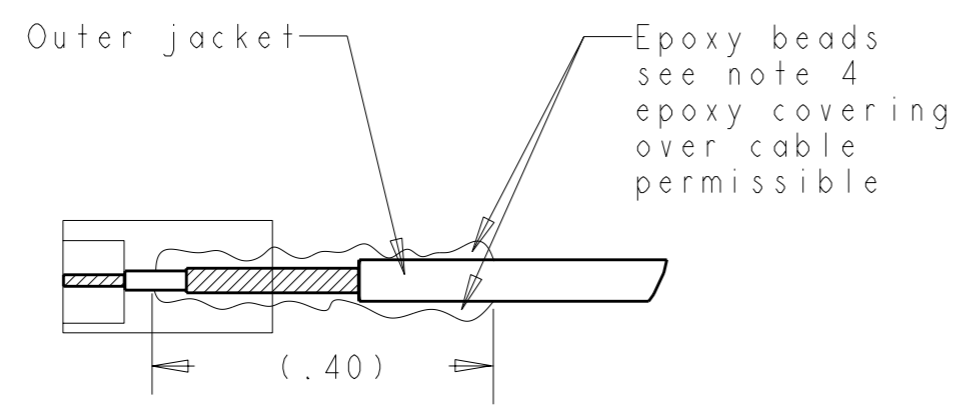
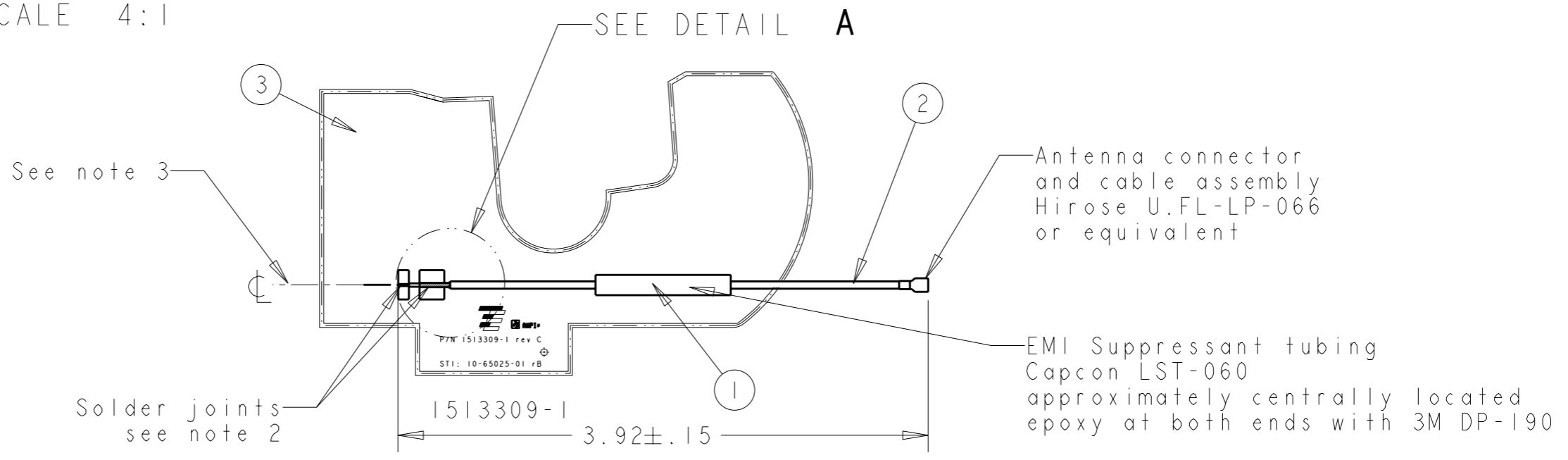
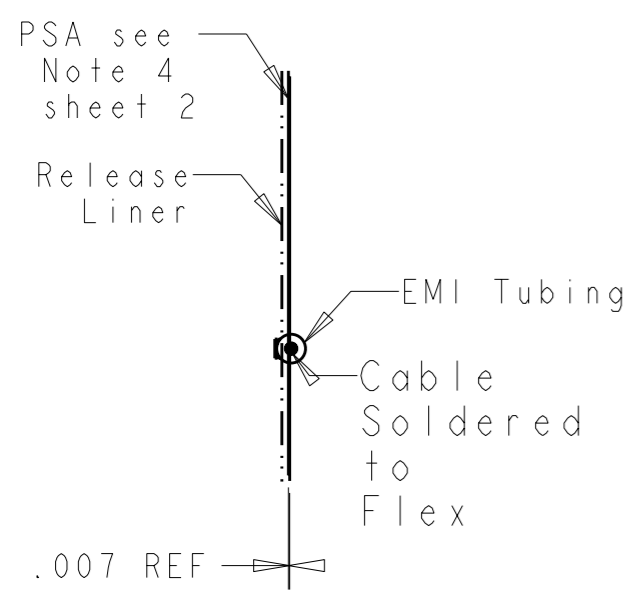


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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
HQ	00				
	4	Epoxy added to cable	28JAN2004	DJL	MAH
	A	Part status change	29MAR2004	DJL	MAH
	B	New tubing added / epoxy added	18JUN2004	DJL	MAH
	C	Added notes and updated logo	24APR	VG	MAH



DETAIL A
SCALE 4:1



NOTES: UNLESS OTHERWISE SPECIFIED:

1. Package items in accordance with STI general packaging specification 50-04100-013.
2. Align end of center conductor to outer edge of solder pad as shown. Solder exposed shield to flex as shown.
3. Position cable at the vertical center of the solder pads as shown. ±0.02in.
4. Apply epoxy (3M DP-190) over solder joint and up on outer jacket approximately as shown.
5. Part is RoHS compliant per Tyco Electronics Standard 230-702.

PLATING/PROCESS	MATERIAL	PART NUMBER	QTY.	ITEM NUMBER
SOLDER	1513309-2 1513297-1	1513309-1	-	-
-	FPC	1513309-2	1	3
-	CABLE WITH CONNECTOR	1513297-1	1	2
-	CAPCON LST-060	1513429-1	1.00 ± .10 inch	1

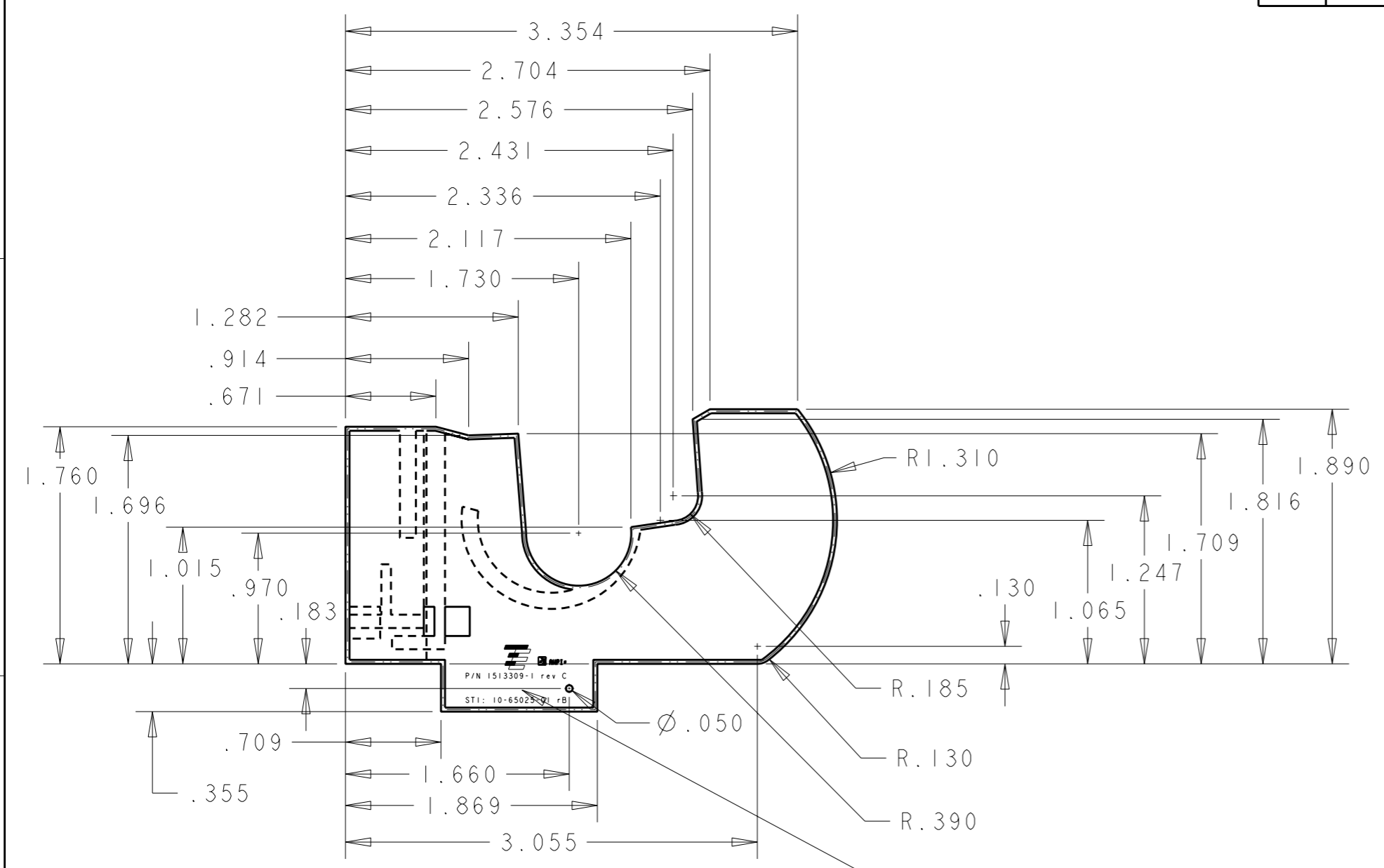
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DIMENSIONS: INCHES	TOLERANCES UNLESS OTHERWISE SPECIFIED:
	0 PLC ±0.1
	1 PLC ±0.05
	2 PLC ±0.02
	3 PLC ±0.005
	4 PLC ANGLES ±0.001° ±1°
MATERIAL -	FINISH -

DWN DJL	29MAR2004	Tyco Electronics Rochester, New York 14623	
CHK -	-	NAME	
APVD -	-	Antenna Assembly Gemini WAN	
PRODUCT SPEC -	-	SIZE A3	CAGE CODE 00779
APPLICATION SPEC -	-	DRAWING NO C-1513309	RESTRICTED TO -
WEIGHT -	-	SCALE 1:1 SHEET 1 OF 2 REV C	
CUSTOMER DRAWING			

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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
HQ	00	-	SEE SHEET 1	-	-



- NOTES: UNLESS OTHERWISE SPECIFIED:
- General Tolerances (Unless Otherwise Specified):
 Copper pattern: ± .002
 Board outline: ± .008
 Board outline to copper pattern: ± .005
 Board outline to soldermask: ± .008
 Vendor to compensate for over/under etch factor.
 - Immersion tin or gold finish as specified on PO or TE Engineering approved equivalent.
 - Workmanship per STI specification SS-03800-57.
 - Flex thickness to be .007±.001 including adhesive, without release liner.
 - Label part using a non-conductive white epoxy ink approx. as shown. Label to include logo(s), part number, and latest revision. Character height range: .06" - .125".
 - Apply 3M F-9460PC VHB adhesive transfer tape with release liner.
 - Solder mask is .015" from edge of board all around.
 - Refer to gerber file: 100233revC.zip.
 - Part is RoHS compliant per Tyco Electronics Standard 230-702.

1513309-2

See note 3

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DIMENSIONS: INCHES		CHK -	APVD -	NAME Flex Circuit Gemini WAN	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±0.1 1 PLC ±0.05 2 PLC ±0.02 3 PLC ±0.005 4 PLC ±0.001 ANGLES ±1°		PRODUCT SPEC -	APPLICATION SPEC -	SIZE A3	CAGE CODE 00779
MATERIAL -		FINISH -	WEIGHT -	DRAWING NO 1513309	RESTRICTED TO -
CUSTOMER DRAWING			SCALE 1:1	SHEET 2	OF 2
				REV C	